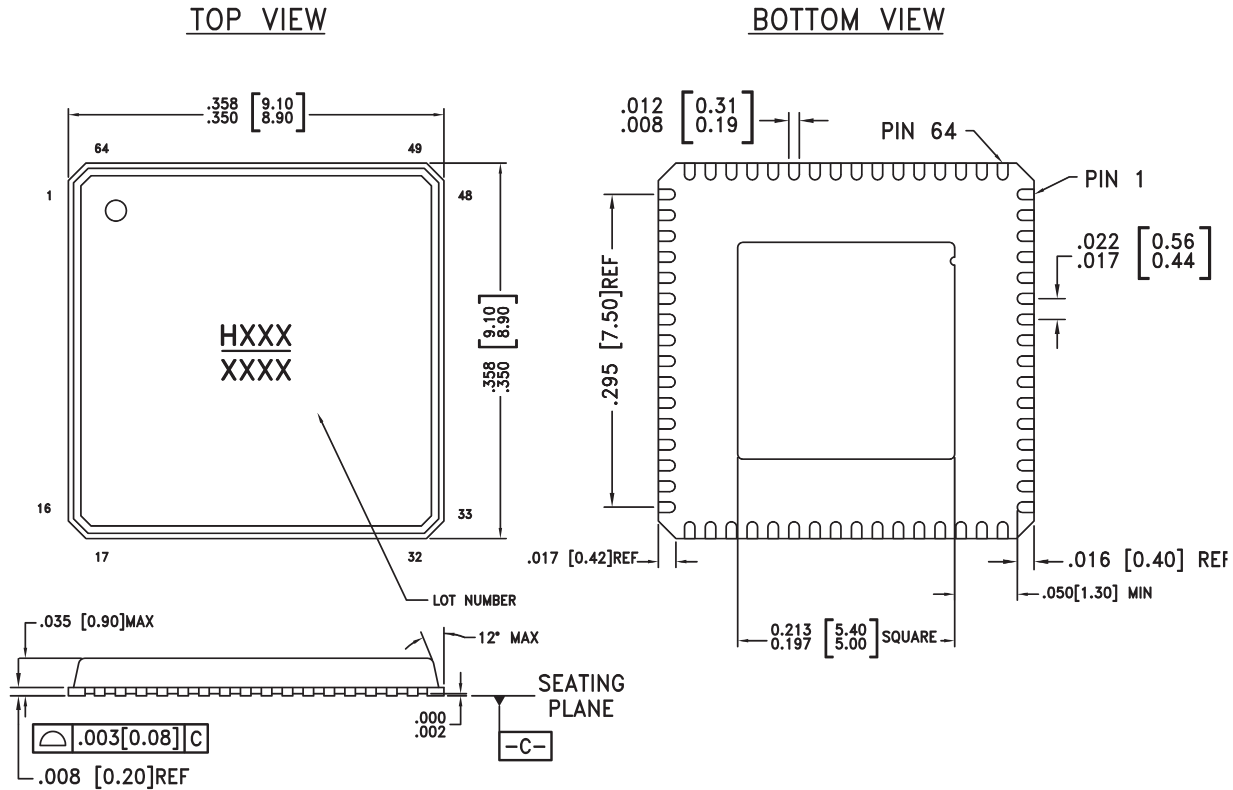
LP9 (E) – 9 x 9 mm QUAD FLATPACK NO-LEAD (QFN) PLASTIC PACKAGE

LP9 (E) Package Outline Drawing



NOTES:

1. PACKAGE BODY MATERIAL: LOW STRESS INJECTION MOLDED PLASTIC SILICA AND SILICON IMPREGNATED.
2. LEAD AND GROUND PADDLE MATERIAL: COPPER ALLOY.
3. LEAD AND GROUND PADDLE PLATING: 100% MATTE TIN.
4. DIMENSIONS ARE IN INCHES [MILLIMETERS].
5. LEAD SPACING TOLERANCE IS NON-CUMULATIVE.
6. PAD BURR LENGTH SHALL BE 0.15mm MAX. PAD BURR HEIGHT SHALL BE 0.25mm MAX.
7. PACKAGE WARP SHALL NOT EXCEED 0.05mm
8. ALL GROUND LEADS AND GROUND PADDLE MUST BE SOLDERED TO PCB RF GROUND.
9. REFER TO HITTITE APPLICATION NOTE FOR SUGGESTED PCB LAND PATTERN.

Part Number Suffix	Package Body Material	Lead Finish	MSL Rating	Package Marking [3][4]
LP9	RoHS Compliant Mold Compound	Sn/Pb Solder	MSL1 [1]	HNNN XXXX
LP9E	RoHS Compliant Mold Compound	100% matte Sn	MSL1 [2]	HNNN XXXX

[1] Max peak reflow temperature of 235 °C
[2] Max peak reflow temperature of 260 °C
[3] 4-Digit lot number XXXX
[4] 3-Digit part number NNN

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